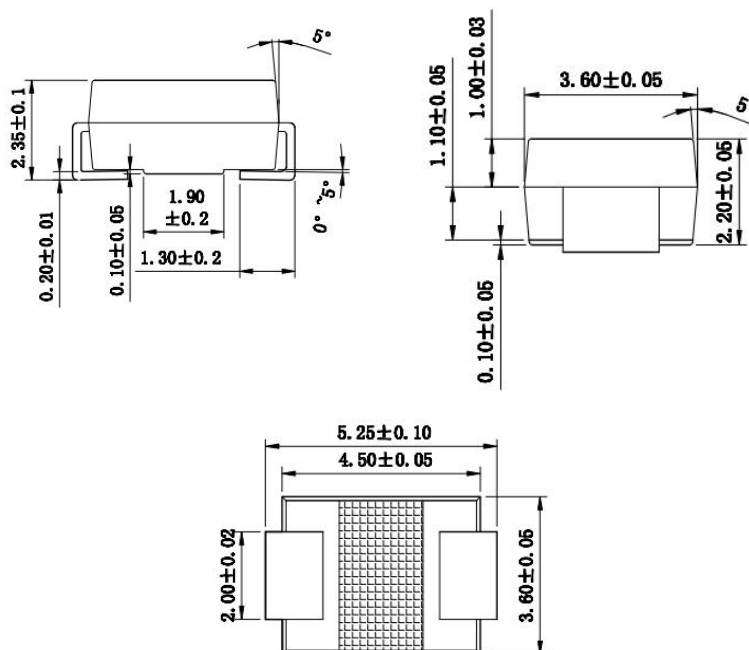


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Open Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 250°C/10 seconds at terminals

DO-214AA/SMB



Mechanical Data

Case: JEDEC 60B molded plastic body

Terminals: Solderable per MIL-STD-750, Method 2026

Polarity: Polarity symbol marking on body Mounting

Position: Any

Weight : 0.005ounce, 0.138grams

Maximum Ratings And Elect Characteristics

Ratings at 25 C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Dimensions in inches and (millimeters)

Type Number	SYMBOL	S3A	unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	V
Maximum RMS Voltage	V_{RMS}	35	V
Maximum DC blocking Voltage	V_{DC}	50	V
Maximum Average Forward Rectified Current .at $T_A = 55^\circ\text{C}$	$I_{F(AV)}$	3	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	100	A
Maximum Forward Voltage at 1.5A DC	V_F	1.1	V
Maximum DC Reverse Current @ $T_A = 25^\circ\text{C}$ At rated DC blocking voltage @ $T_A = 100^\circ\text{C}$	I_R	10.0	μA
		100	
Typical Junction Capacitance (Note1)	C_j	35	pF
Typical Thermal Resistance (Note 2)	$R_{(JA)}$	40	$^\circ\text{C}/\text{W}$
Storage Temperature	T_{STG}	-55 to +150	$^\circ\text{C}$
Operation Junction Temperature	T_J	-55 to +150	$^\circ\text{C}$

Note: 1. Pulse Test with $PW=300\mu\text{sec}$, 2% Duty Cycle.

2. Mounted on P.C.Board with 5.0mm2(.013mm thick)copper pad areas.



FIG.1 – FORWARD DERATING CURVE

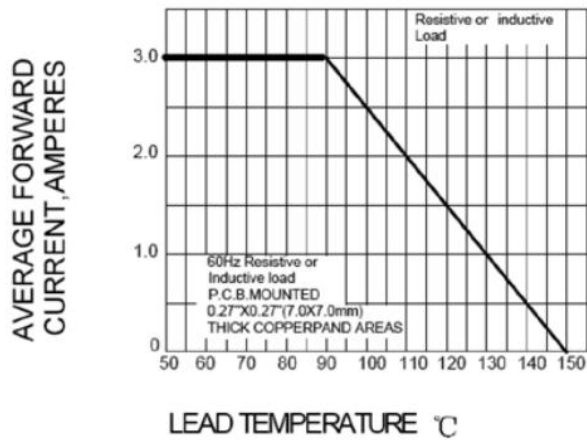


FIG.2 PEAK FORWARD SURGE CURRENT

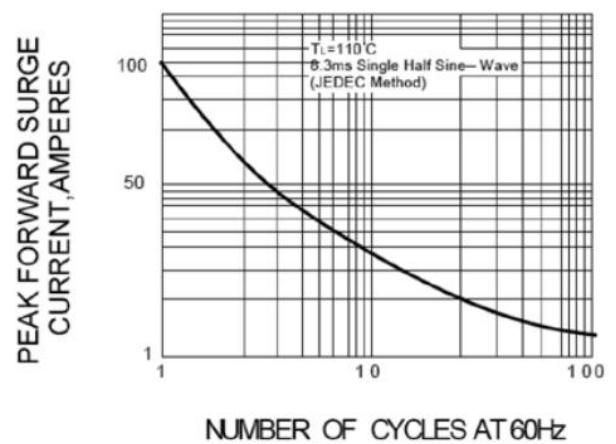


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

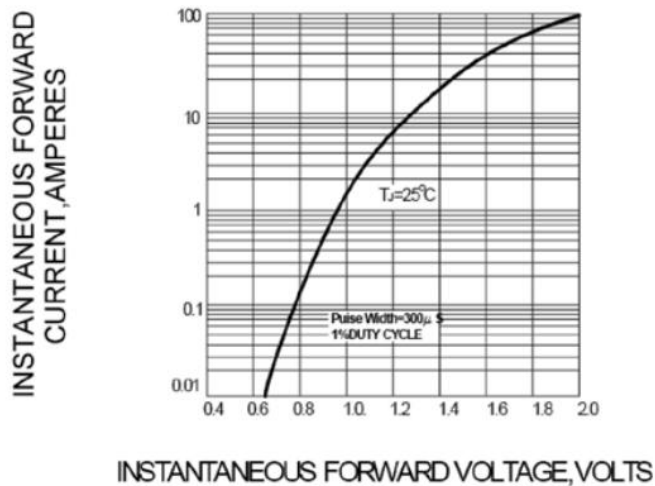


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

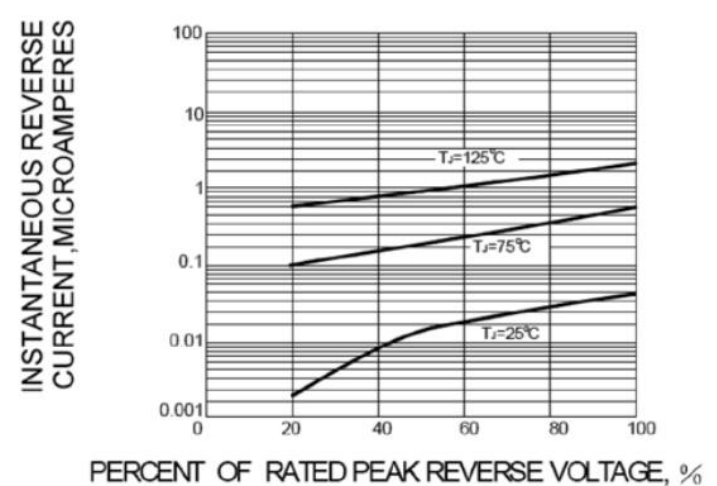


FIG.5-TYPICAL JUNCTION CAPACITANCE

